

TGAN

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Leading the GaN Revolution

Fiscal Q1'23 Investor Update

August, 2022 | NASDAQ: TGAN

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Key Investment Highlights

GaN Power Semiconductor Pioneer and Leader

Disruptive Technology

GaN Enables Next Generation Power Conversion Solutions – 99% Efficiency¹, 50% More Compact/Lightweight, Lower System Cost

Large Market Opportunity

Transphorm's GaN Solutions will Enable the Future of Electric Vehicles and Fast-charging for 5G – Contributing to GaN TAM growing to \$6B² in 2026

Validation From Blue Chip Partners and Customers

Including KKR, SAS, Nexperia, Yaskawa, Marelli, Microchip, Diodes and the U.S. DoD(Navy), DOE



Ramping Commercially with Strong Manufacturing Base

Technology and Product Development completed, Integrated Manufacturing, \$24.1M FY-22 Revenues, Target >50% LT CAGR

Best-In-Class Differentiated GaN Technology + Industry's Strongest IP

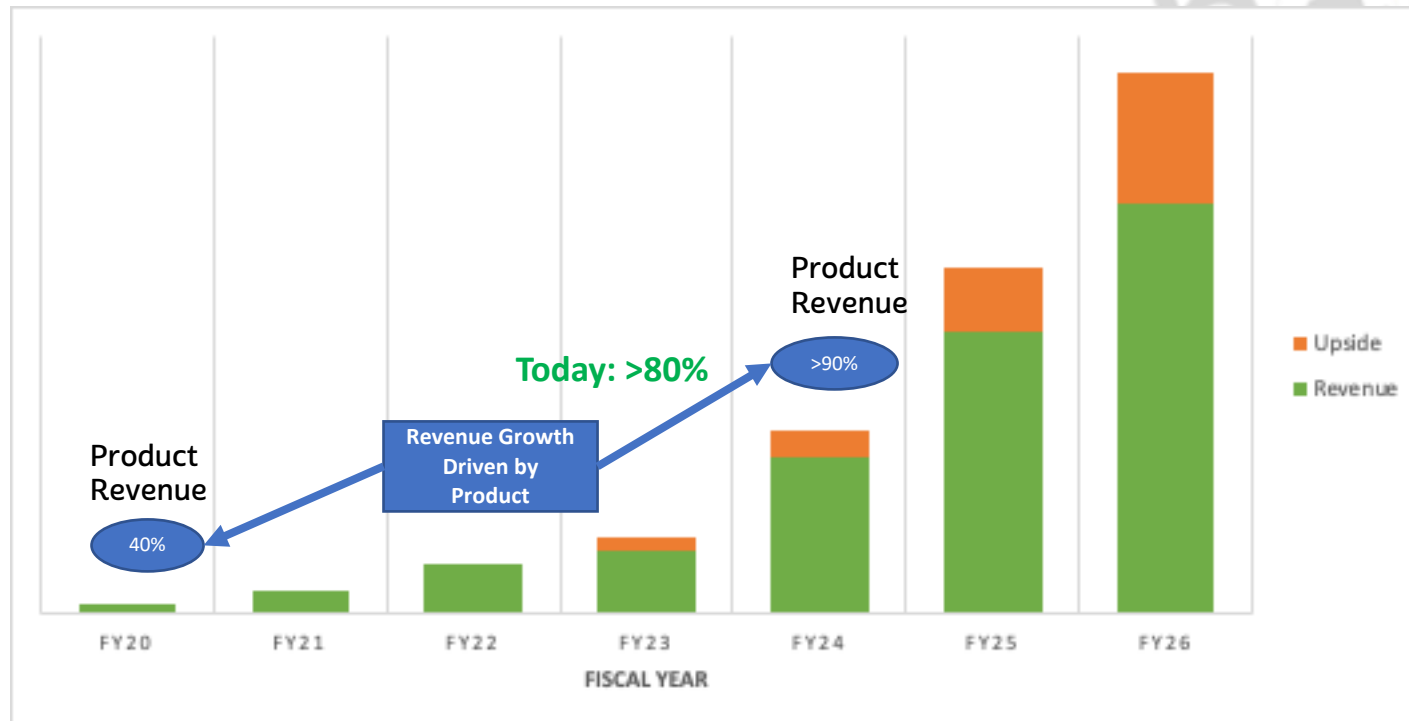
IP Portfolio Appraised in Excess of \$200M³
Leader in Quality + Reliability, > 60 Billion Field hours, Silicon-like Reliability⁴

Team Led by World-Renowned GaN Experts

Proven Leadership, 18 PhDs and Over 300 Years of GaN Expertise

Target Operating Model

Building a High-Growth, Product Driven Cash Generating Business



Operating Guidelines:

- Rapid top-line growth and GaN adoption across multiple end markets
- OpEx for continued development of best-in-class products and IP portfolio
- CAPEX investment for increased

Target Model:

5-year CAGR
range: 50%+

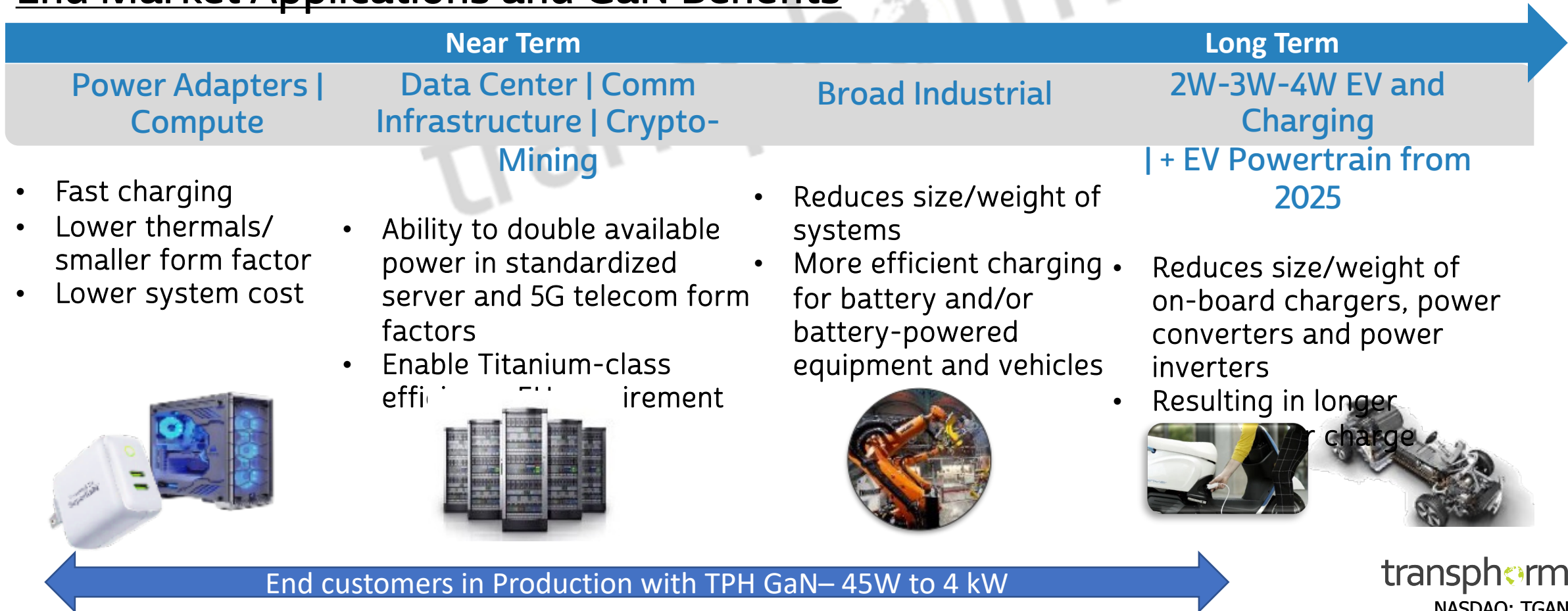
Gross
Margin: 40%+

Operating
Margin: 20%+

Targeting \$3 Billion Power Market Opportunity in 2023

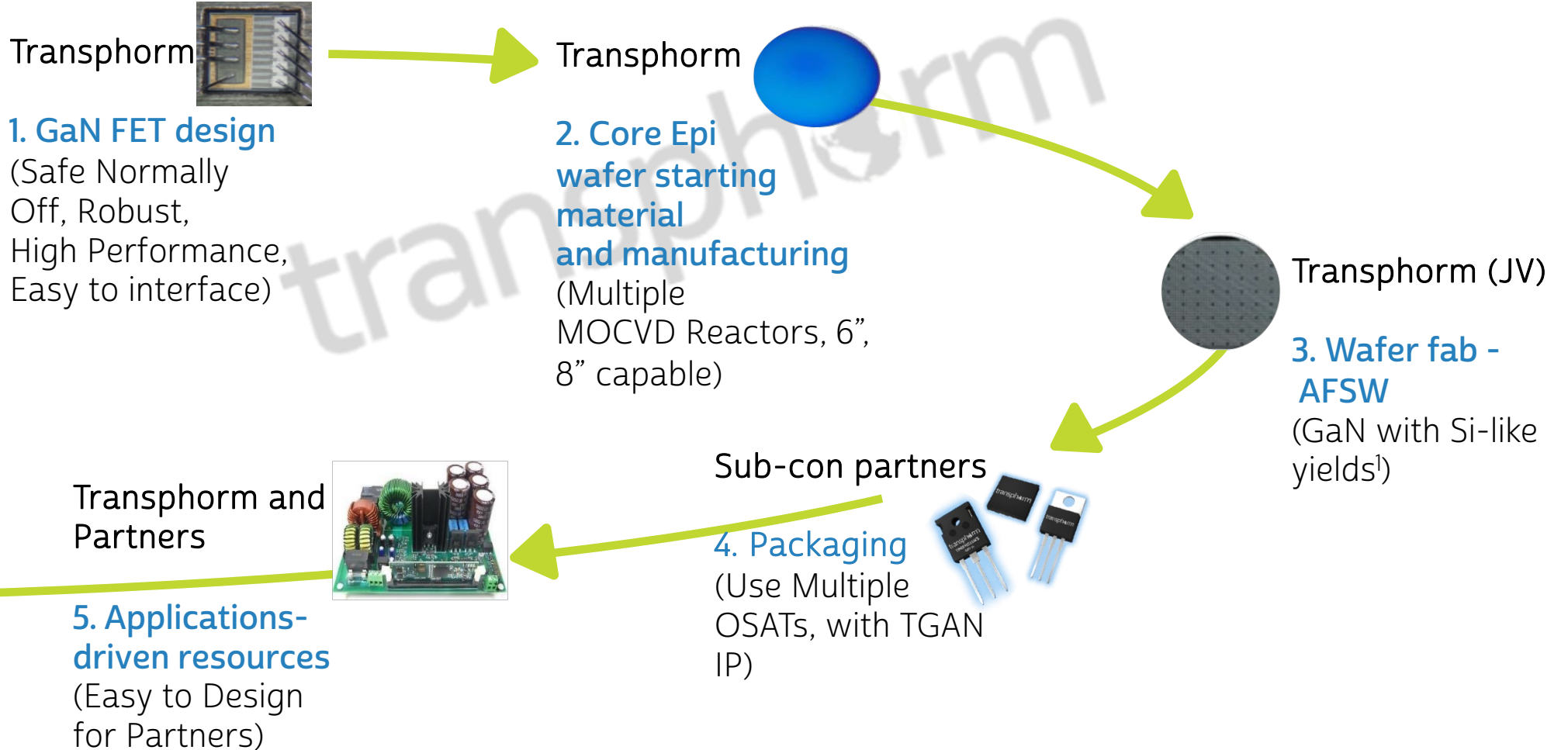
Upside to TAM from Electric Vehicle Powertrain starting in 2025

End Market Applications and GaN Benefits



TGAN Owns GaN Wafer Production Supply Chain

Asset-Light, Vertically Integrated Manufacturing Driving Innovation



1) P. Parikh et. al., GaN Power Commercialization with Highest Quality-Highest Reliability 650V HEMTs- Requirements, Successes and Challenges, 2018 IEEE International Electron Devices Meeting (IEDM), Dec 2018

TPH GaN vs. e-mode GaN: Why We Win!

Key Factors	Silicon MOSFET	e-mode GaN	Transphorm GaN FET
Ease of use (std. drivers, agnostic to controllers)	●	●	●
Size (form factor) and Speed (frequency)	●	●	●
Performance (efficiency) ¹	●	●	●
Added BoM components (cost) ²	●	●	●
Reliability and Robustness ³	●	●	●

 Strong
 Medium
 Weak

^{1,2}Based on multiple public and internal reference designs, <https://www.transphormusa.com/en/reference-design/tsadp-sil-usbc-65w-rd/>
³Impact of OFF-state Gate Bias on Dynamic R_{on} of p-GaN Gate HEMT (33rd ISPSD, 2021)

TGAN FET: Higher Range, Reliability & Performance Spanning Low to High Power

Why Transphorm Wins:

- Transphorm adopted in many more markets
- “e-mode” input interface is weaker – hard to operate in widely used *TO Packages* for higher power
- Superior Dynamic performance from TGAN FET – *Higher performance, from smaller GaN die*
- Proven reliability & manufacturing for scaled device – *10 kW capable single GaN device in production*
- Higher power => higher energy and emissions impact, *e.g. Blockchain consumes 120 TWH, TGAN’s 1% efficiency gain => 1TWH + (> 125 lbs of CO₂ emissions / TGAN Device²), >50,000 metric tons in 2022 alone (single market application!)*

In Production ¹			
Markets	GaN e-mode or “IC”	GaN FET	Power Range TGAN Wins
Adapters	✓	✓	30-250W
Datacenters	✗	✓	800-3200W
Gaming (Desktop)	✗	✓	1600W
Blockchain	✗	✓	1600-3600W
Industrial (≥ 500 W)	✗	✓	500-3000W
Aerospace			420-1200W

¹ production with customers’ systems

2. Based on existing rectifiers with 92% efficiency | Source: EPA estimated one kWh produces 1.52 pounds of carbon dioxide (excl. line-losses).

Customers Select Transphorm GaN – Adapters & Chargers, 60 design-ins

Ultra slim, light weight (65 W)



Compact, high efficiency (68 W)



Quick Charge-5, USB C PD (100 W)



Compact Power Bar, 65W 1A-1C



Compact 100W 2C-1A



High-efficiency (65 W)



Wall plug – high efficiency, compact (35 W)



Note book – small size, 200 KHz high speed (160 W)



Compact 30W Power Bar



Multi out 150W (2C-1A)



Compact, efficient USB-C (65W)



New 65W 2C-1A (Phihong)



New 65W 2C-1A



New 120W 2C-2A-Axial



Ultra compact 240W

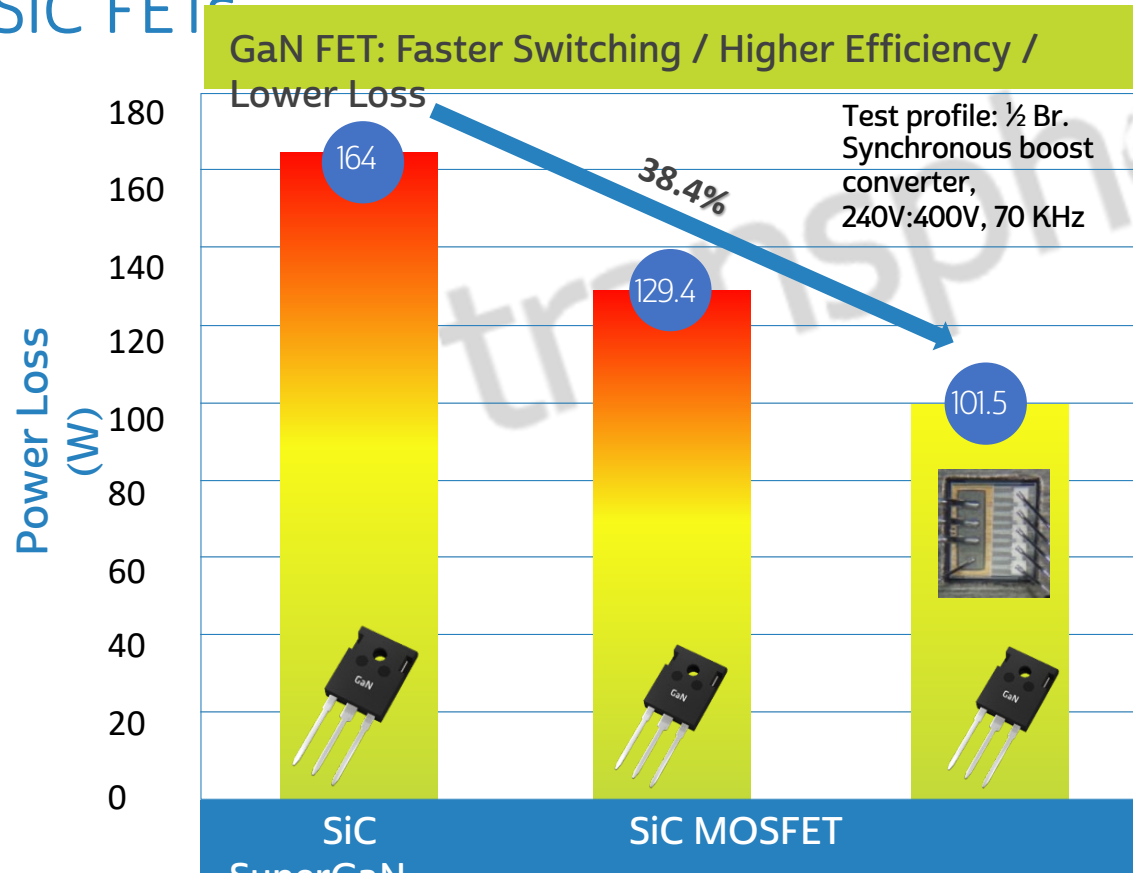


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NASDAQ: TGAN

Transphorm GaN FET Outperforms the

SuperGaN® offers reduced power loss (25-38%)
over SiC FETs



Device Power Loss Comparison (9.2 kW)

(Limited due to SiC FET junction temperature)

Recent 3rd party independent validation: 15-20% loss reduction (0.5-1% point efficiency improvement) at 5 kW in a resonant converter ¹

1. PCIM 2022, Technical Paper, Alejandro Llop et. al., "A Comparison among Wide Bandgap Devices using a CLLLC Bidirectional Resonant Converter"

Customers Select Transphorm GaN – High

Power, Efficient, Reliable, Highest Performance, Ease of Drivability and Designability



“The Corsair AX1600i is the **best PSU** that money can buy today, period.”
tom's HARDWARE



“Transphorm’s GaN in a totem-pole PFC configuration proved the **most reliable, highest performing** solution possible today,”



“Ease of drivability and designability— **does not require custom drivers**. Proven reliability— JEDEC and AEC-Q101”

“Based largely on the power semiconductors’ proven quality and reliability as well as the team’s reputation for **successful collaboration**,”



“We’re expanding the reach of **medical care**, and Transphorm’s GaN is helping us do it”

NEW



GaN benefit of low switching loss, 1st gaming psu with GaN in ASUS

NEW



GaN Enables Future of Next-Gen Electric Vehicles: 2W/3W/4W

EV challenges for existing

Lower Watts / Cubic Inch

Power Loss

Heat Constraints

Limited Driving Distance

Higher Cost & Power Demand



**Transphorm Gen IV
650V 35mΩ GaN FET**

- Automotive qualified (AEC) today

- Charger / Converter / Inverters for EVs
- Earlier penetration into 2W-3W EVs (CY2023)
- Staying ahead: R&D for 1200V¹ with GaN for higher battery voltage EVs (taking on SiC higher Voltage FETs)

Faster Charging & Increased Range w/

Future of EV with GaN-based solutions

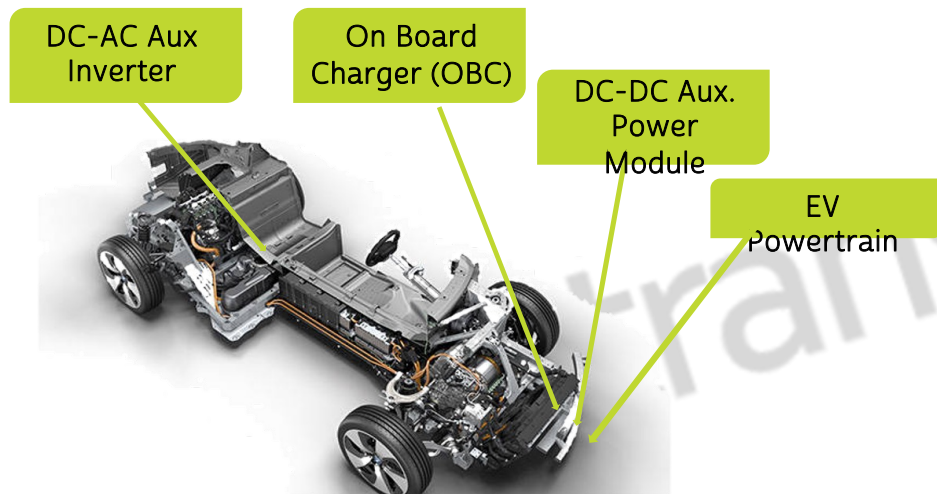
GaN-enabled Power Solution Benefits¹:

- + 2x More Watts / Cubic Inch, Faster Charging
- + Less Power Loss (~20%)
- + Reduced Size (~50%)
- + Increased Range

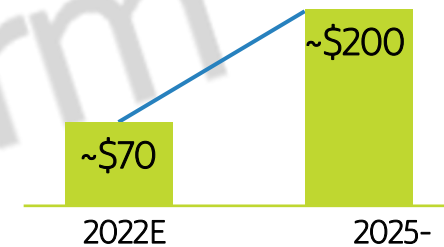
Accelerating Opportunity for GaN Enabled

Power in EV

1. GaN Opportunities in EV, 4W

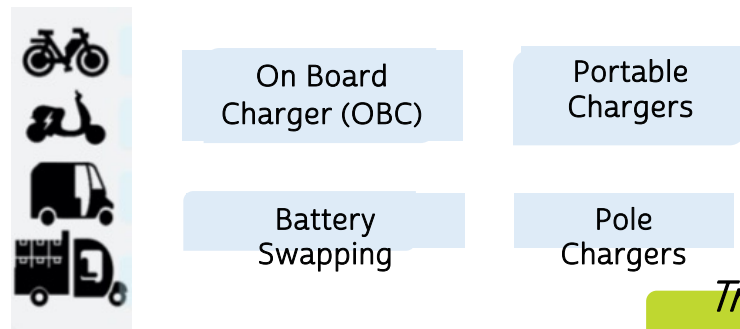


1. Addressable GaN \$ Content/EV, 4W²



- Well-positioned for automotive opportunity with leading products, strategic partners
- EV Adoption increasing to 32 million (44 million - hyper adoption) vehicles by 2030¹

2. GaN Opportunities in EV, 2W, 3W



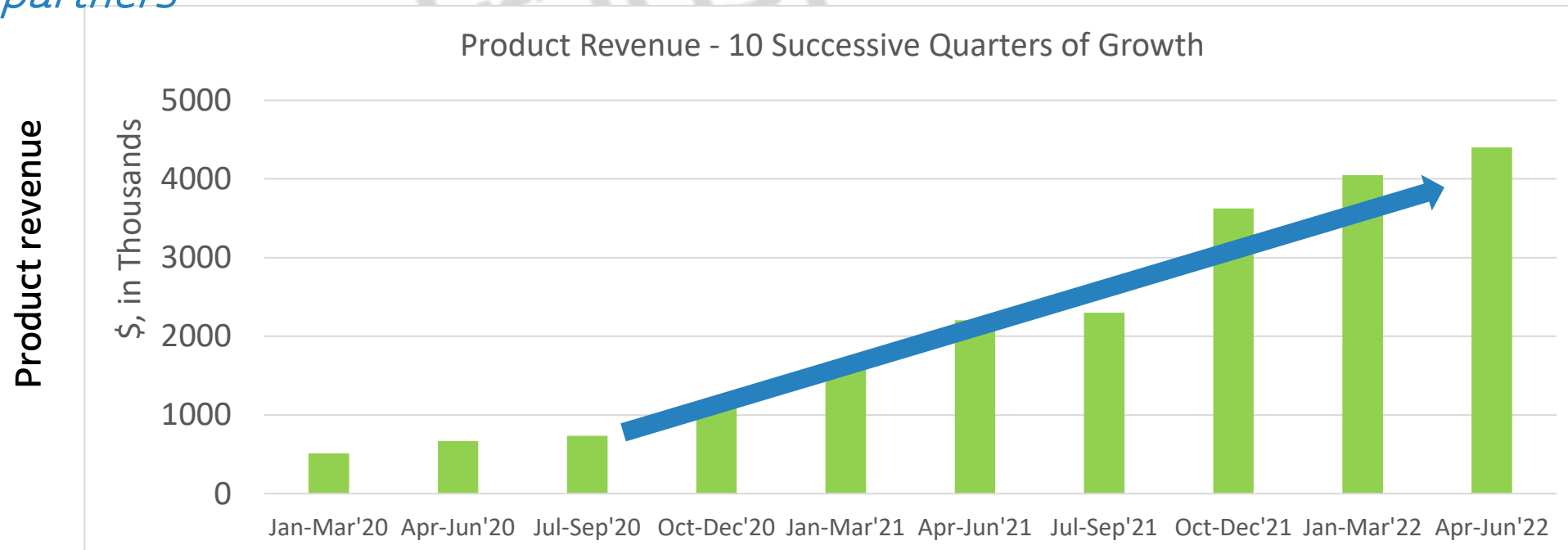
2. EV 2W, 3W Market

- TGAN FET already proven in battery-swapping
- Potential to address 75 Million 2W/3W WW (Asia dominated)³, \$8-10/vehicle

Transphorm GaN AEC-Q101 (Auto) Qualified NOW

Strong QoQ of Product Revenue Growth

- *Maintaining leadership in higher power markets / 1-5kW segment (1 large device ~ 8 smaller Adapter/charger devices): Across the board wins and continued supply in gaming, blockchain, energy, medical*
 - *>60% revenues from high power*
- *Gain share in Adapter/chargers with proven superior performance, strong solutions partners*



Key Business Focus – Scaling Product

Revenue Focus on 1) Expanding Capacity 2) Supply Chain and 3) Product Revenue

Key focus area	Achieved	Comments / Upcoming
1. Revenue/Products	<ul style="list-style-type: none"> ✓ \$4.4M Products (Total \$5.2M) 	<ul style="list-style-type: none"> • 10th sequentially higher Quarter • Record backlog in place
2. Adapters/Chargers: Design-ins, Production, Solutions (45W – 250W)	<ul style="list-style-type: none"> ✓ Design-Ins: 60 (several added) ✓ In Production: >20 ✓ Solutions/Ref designs: >12 (7 new Ref Designs) 	<ul style="list-style-type: none"> • Phihong Win shows design, performance leadership • Easy to use, no added driver, Small die vs. e-mode • Continued POs at major Tier 1s (Laptop, E-retailer)
3. High power: Design-Ins, Production, Ref. Designs (300W-4kW)	<ul style="list-style-type: none"> ✓ Design-Ins: >35 (several added) ✓ In Production: >15 ✓ Eval kits/Ref designs: >8 (1-4kW) 	<ul style="list-style-type: none"> • >60% of revenue High Power • Execution on >500K units PO for 3kW+ • Expand, Penetrate new segments, Lead
4. Product SKUs and Qualification	<ul style="list-style-type: none"> ✓ Total: 17 (AEC qualified: 3) – new D2 Pak SMD ✓ 1200V R&D Demo – higher performance vs. SiC (ISPSD – IEEE conference, May 2023) 	<ul style="list-style-type: none"> • Broadest offering (650/900V), • Compact surface-mount & thermally robust TOs • Next: Gen5 AEC qualification
5. Capacity Proof Points	<ul style="list-style-type: none"> ✓ Packaging capacity in place (only in industry for PQFN through TO packages) ✓ Expanding and acquiring new epiwafer capacity 	<ul style="list-style-type: none"> • Continued emphasis on supply chain management • Epi Reactors – Bring existing capacity online and acquire additional reactors (and online in 2nd half of CY23)

Key Business Update – Strategic Partnerships

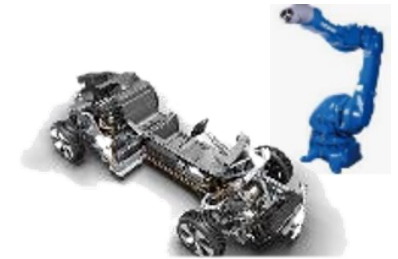
Manufacturing Capacity Increase, Partnerships

- Acquired 2 additional reactors, online in second half CY-2023
- Global Wafers (Partner) – Agreement formally signed, additional \$5m equity via recent Greenshoe.
 - Further epiwafer expansion
- AFSW Fab (Transphorm’s JV) – Managing with GaNovation (Financial-Strategic partner) and investing for CY-2023 to be ready for increasing demand



Industrial and Automotive

- Yaskawa (Industrial) – Program aligned for cost effective innovative solutions for robotic applications
 - Pending \$0.75m development funding completed (July’22)
- Nexperia (Automotive focus) – Continued epi and fab wafer supply, next milestone Gen5 AEC qual
- Japan Automotive: Continuing design-ins with other Japan EV, for CY 2024-25, dc-dc and obc opportunities
 - Started initiatives in EV 2-Wheeler/3-Wheeler (Asia) for faster EV (CY2023) revenue




Government Revenue and Epi Business

- Navy and Govt. Programs –Billing \$0.7m in FQ1’23, current program wraps up in FQ3’23, and now targeting follow-on in FO4’23. Complete 1200V ARPA-E effort.

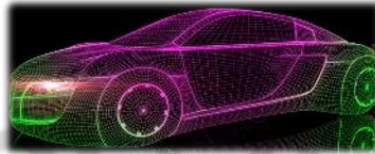


Key Financial Highlights

Record Product Revenue, Stable EPS, TGAN now on NASDAQ

	Q1 FY23	Q4 FY22	Commentary
Revenue	\$5.2m (85% Product)	\$4.9m (80% Product)	<ul style="list-style-type: none"> • 10 successive quarters of revenue growth • Total Revenue increased 5% from Q4, 60% from Q4 FY22 • Product revenue increased 10% from Q4, 101% from Q4 FY22
Gross Margin	21.5%	23.1%	<ul style="list-style-type: none"> • Impact of some cost increases, investment in COG's team • Reduced Government income
OPEX (non-GAAP)	\$5.4m	\$4.7m	<ul style="list-style-type: none"> • \$0.7m increase in quarter • Increases in personnel, G&A (legal, K costs)
EPS (non-GAAP)	(\$0.08)	(\$0.08)	<ul style="list-style-type: none"> • Stable EPS Q to Q
Stockholders Equity		\$42m	<ul style="list-style-type: none"> • \$43.1m cash and cash equivalents • Greenshoe adding \$16m to balance sheet before fees
Operational Notables			<ul style="list-style-type: none"> • Record quarterly product bookings • Backlog in place to support growth • Strong hiring continues across the company • Increased liquidity from trading volumes

Positioned to Grow Across Multiple Segments



5G Market Adoption

Electric Vehicle (EV) Market Adoption

Adoption / Growth

Execution and Expansion

Achieve Target Model

CY 2021-2022

CY 2023

CY 2024+

- Multiple revenue streams in place
- Growing production across multiple segments
- Shipped > 1M units in December 2021
- Continued investment in growth across all aspects of the company
- Investing in capacity increases

- Broad market inflection point
- Ramping revenue across consumer, data centers and blockchain segments
- Continue to scale capacity aggressively
- Initial wins in EV 2W/3W/4W segments
- Continued government contracts

- Continued momentum and broad market expansion
- Automotive adoption growth
- Leader in High Power, EV, Consumer segments
- Positive cash flow generation
- Execute to target model

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Proven Leadership, 18 PhDs and Over 300 Years of GaN Expertise

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Appendices

Financials

Glossary of Terms and Abbreviations

AC – alternating current

AEC-Q101 – Automotive Electronic Council’s electronic components stress qualification standard

AFSW – Aizu Fujitsu Semiconductor Wafer Solution Limited, our joint venture wafer fabrication facility located in Aizu Wakamatsu, Japan

BJT – bipolar junction transistor, a semiconductor device

Bus voltage – voltage into, out of or within connections of a power electronic system

CMOS – complementary MOS (metal oxide semiconductor), widely used semiconductor transistor architecture

D2Pak – a surface mountable version of the TO220 package

DC – direct current

Die/Chip – an individual semiconductor device on the wafer, prior to packaging

EAR – Export Administration Regulation

Epi/Epiwafer/Epimaterials – GaN device layers grown on a substrate, from which active GaN-based devices are subsequently manufactured in a wafer fabrication facility

Fab – fabrication, generally referring to a semiconductor wafer fabrication facility

FET – field effect transistor, a type of switching transistor

Figure of Merit - a quantity used to characterize the performance of a device, system or method, relative to its alternatives

FIT – failure in time, referring to the expected number of device failures per billion hours of operation

GaN – gallium nitride

HEMT – high electron mobility transistor, a type of switching transistor with superior electronic properties

IGBT – insulated-gate bipolar transistor, a three-terminal power semiconductor device primarily used as an electronic switch

JEDEC – Joint Electron Device Engineering Council, an independent semiconductor engineering trade organization and standardization body that represents all areas of the electronics industry

LIDAR – light detection and ranging, a remote sensing method that uses light in the form of a pulsed laser to measure distance

Lossy – in the context of switching devices, subject to loss of power due to switching inefficiencies and other factors

MOCVD – metal organic chemical vapor deposition, a technique for layering GaN layers onto substrates such as a silicon substrate and making the starting GaN semiconductor material (i.e., an epiwafer)

Moore’s law – the observation that the number of transistors in a dense integrated circuit doubles about every two years

MOSFET – metal-oxide-semiconductor field-effect transistor, a type of transistor

Normally Off – default position is off

Power converters / Inverters – electronic systems used to convert electricity from AC to DC (such as a charger), DC-AC (such as an inverter) or in some cases AC-AC or DC-DC within the systems converting from one voltage level to another

PQFN – power quad flat no lead package, a compact surface mountable package used in power semiconductors

RF – radio frequency

SCR – silicon controlled rectifier, an early semiconductor switching device

Si – silicon

SiC – silicon carbide

TO – transistor outline leaded packages commonly used in power semiconductors (such as TO220, TO247)

Income Statement

Record Product Revenue, Stable NON-GAAP performance

	June 30, 2022	March 31, 2022	June 30, 2021
Revenue, net	\$ 5,156	\$ 4,927	\$ 3,216
Cost of goods sold	4,050	3,789	2,567
Gross profit	1,106	1,138	649
Operating expenses:			
Research and development	1,740	1,632	1,823
Sales and marketing	1,083	1,047	687
General and administrative	3,317	2,917	2,743
Total operating expenses	6,140	5,596	5,253
Loss from operations	(5,034)	(4,458)	(4,604)
Interest expense	182	181	204
Loss in joint venture	582	677	1,490
Changes in fair value of promissory note	-	-	1,024
Other income, net	(445)	(317)	(270)
Loss before tax expense	(5,353)	(4,999)	(7,052)
Tax expense	-	-	-
Net loss	\$ (5,353)	\$ (4,999)	\$ (7,052)
Net loss per share - basic and diluted	\$ (0.10)	\$ (0.09)	\$ (0.17)
Weighted average common shares outstanding - basic and diluted	54,404,830	53,343,862	40,637,213

Revenue of \$5.2m in Quarter

- 10th successive quarter of product revenue growth
- Product revenue now over \$4.4m (10% q/q growth)

Gross Margins

- 22% in Q1
- Reduced government revenue in Q
- Impacted by higher cost of raw materials and continued investment in production team

Operating Expenses

- OPEX increased q/q
 - G&A increases driven by increased legal and audit fees together with recruitment costs
 - Reduced ONR as lower billings in quarter

Non-GAAP EPS (\$0.08)

Balance Sheet

Strong long term cash stability

	June 30, 2022 (unaudited)	March 31, 2022 (audited)	June 30, 2021 (unaudited)
Assets			
Current assets:			
Cash and cash equivalents	\$ 42,613	\$ 33,435	\$ 1,962
Restricted cash	500	500	500
Accounts receivable	3,203	2,558	2,247
Inventory	6,963	6,330	2,924
Prepaid expenses and other current assets	2,575	1,971	2,160
Total current assets	55,854	44,794	9,793
Property and equipment, net	2,199	1,649	1,832
Operating lease right-of-use assets	3,448	-	-
Goodwill	1,056	1,180	1,303
Intangible assets, net	543	617	839
Investment in joint venture	339	143	-
Other assets	291	263	267
Total assets	\$ 63,730	\$ 48,646	\$ 14,034
Liabilities and stockholders' equity (deficit)			
Current liabilities:			
Accounts payable and accrued expenses	\$ 4,674	\$ 3,588	\$ 3,744
Deferred revenue	354	346	1,016
Development loan	-	-	8,000
Accrued interest	182	180	166
Unfunded commitment in joint venture	-	-	1,339
Accrued payroll and benefits	1,120	1,171	1,582
Operating lease liabilities	521	-	-
Total current liabilities	6,851	5,285	15,847
Revolving credit facility	12,000	12,000	12,000
Promissory note	-	-	17,190
Operating lease liabilities, net of current portion	2,941	-	-
Total liabilities	21,792	17,285	45,037
Commitments and contingencies			
Total Stockholders' equity (deficit)	41,938	31,361	(31,003)
Total liabilities and stockholders' equity (deficit)	\$ 63,730	\$ 48,646	\$ 14,034

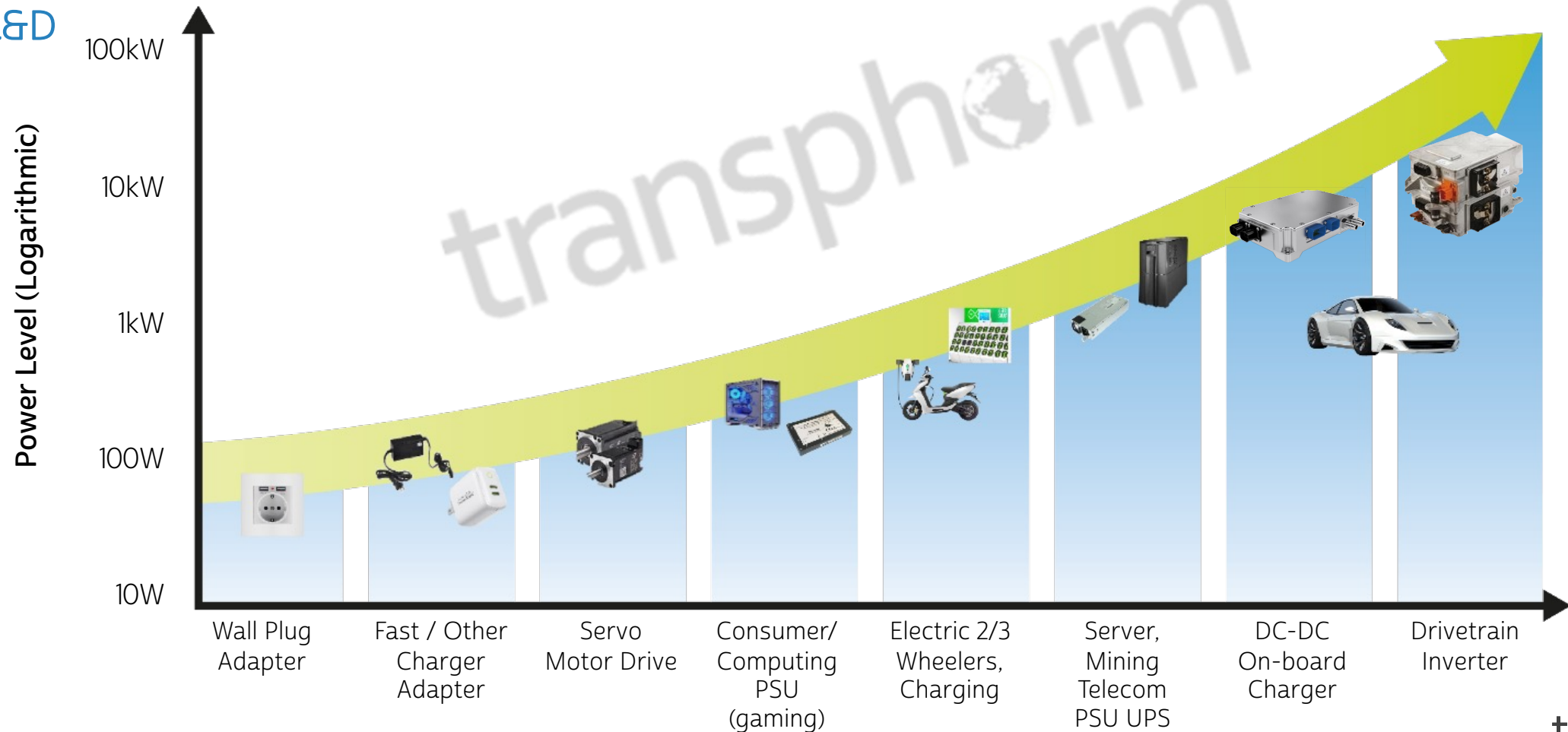
Notables

- Cash and cash equivalents of \$43.1m
 - Greenshoe raised \$16m before fees (\$15.7m after fees)
 - Offset by ongoing operational burn - \$6.1m before CAPEX (flat to Q4'FY22)
- Inventory increased to support backlog growth
- Yaskawa loan (\$15m) converted to equity
- Development loan deliverables met
- Revolving credit facility (\$12m) – due Q1FY24

Solid increase in trading volume

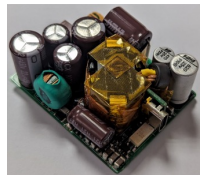
Comprehensive GaN Product Portfolio: 45 W to +10 kW

TGAN Core Platform Spanning the Power Spectrum: Wide breadth of 650V, 900V JEDEC/AEC-Q101 Qualified Products, 1200V and short circuit in R&D



TGAN: Si like ease of use Expands Partnership in 45-250W Solutions

Design Company, Topology, and Power Density														
45 W			65 W			90 to 110 W			120 to 150 W			200-250 W		
Design	Topology	W/in ³	Design	Topology	W/in ³	Design	Topology	W/in ³	Design	Topology	W/in ³	Design	Topology	W/in ³
transphorm	QRF	24	transphorm	QRF	25	transphorm	PFC+QRF	18*	DIODES	PFC/LLC	16	transphorm	PFC/LLC	25 (PCB)
External and In-wall			Silanna	ACF	30	Silanna	ACF	20	New	PFC/LLC	15*	New	PFC/LLC	15*
Supported by partners			DIODES	ACF	30	DIODES	ACF	20	Supported by partners			Supported by partners		



100W



150W



240W

transphorm
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* Including full casing

Leadership in High-Power GaN – Secured new PO

>500,000 units
Efficient, Reliable, High Performance, Patented GaN Architecture

Block Chain Computing – Power Hungry Systems requiring Titanium efficiency



3kW+



- Consumes ~120 TWh, equivalent to small country
- TGAN solutions can enable up to 1% higher efficiency
- 230 V_{AC} (> 125 lbs of CO₂ emissions / TGAN Device¹)
- Greater than 50,000 metric tons in 2022

Notes:

1) Based on compliance estimates done for a 5 MW data center.

2) Based on existing rectifiers with 92% efficiency | Source: EPA estimated one kWh produces 1.52 pounds of carbon dioxide (excl. line-losses).

3) European Union's Ecodesign Directive (Directive 2009/125/EC).

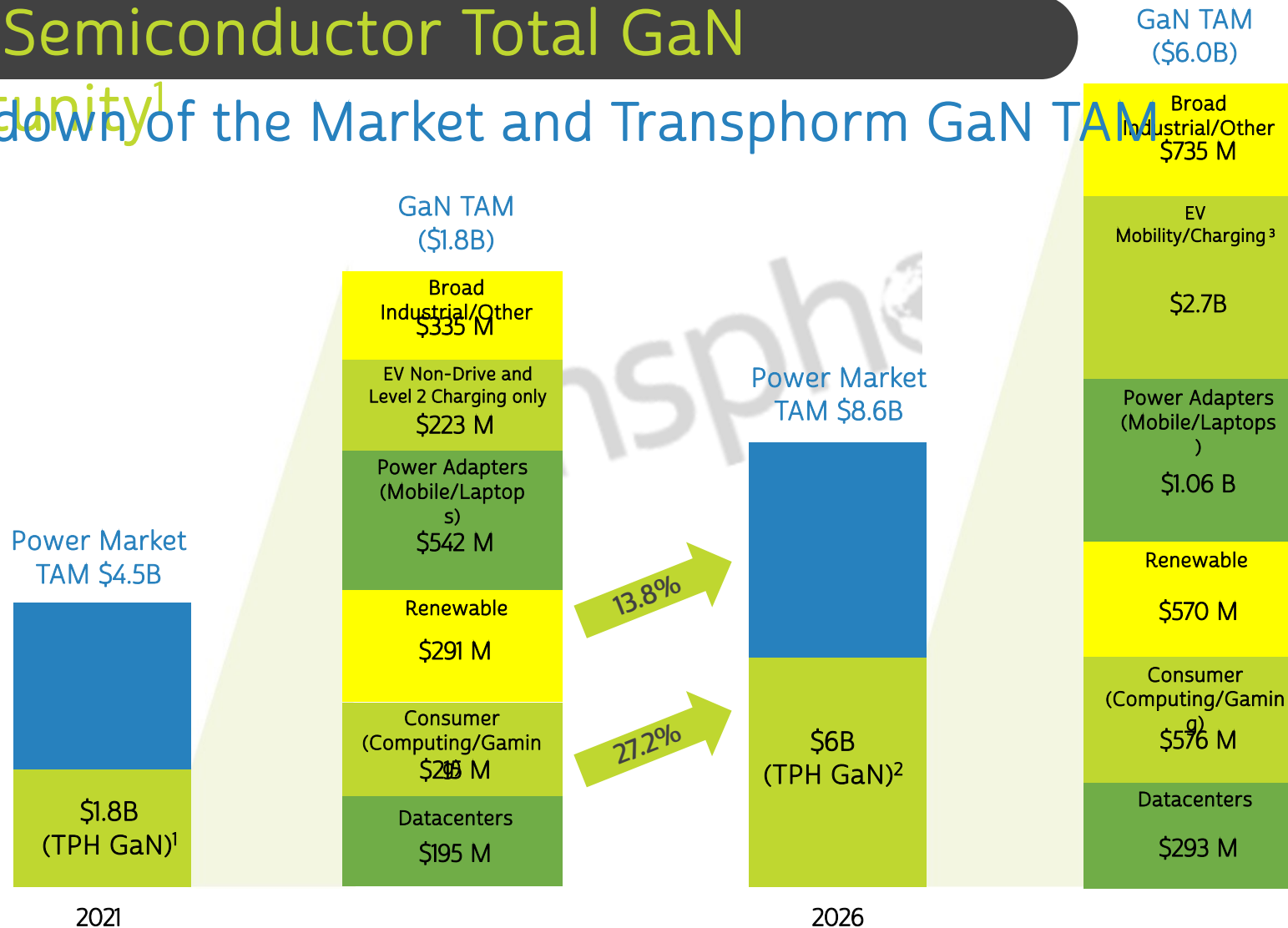
Data Center Server Power – We have enabled Titanium performance for > 4 years



- 5 MW Data center, \$103K saved / year, 397 tons reduced carbon footprint²
- Regulations like EU Ecodesign³ in 2023 expected to accelerate GaN adoption
 - Increased order from existing customer

Power Semiconductor Total GaN Opportunity!

A Breakdown of the Market and Transphorm GaN TAM



1 Market access based on current, future device offerings with operations to support shipments. Does not include the adoption of GaN technology nor Transphorm's yearly adoption rate
 2 Shows the breakout; potential GaN market sizes, does not include any adoption rate
 3 Includes modules for EV inverter and EV fast charging starting in 2024 and beyond
 4 See appendix for references

Transphorm Advantage: Enabling Customers by Taking GaN Benefits to the Next Level

Faster, Smaller, More Efficient and Robust Solutions

Intrinsic Benefits of GaN	
Performance	<ul style="list-style-type: none">• Field-proven best-in-class efficiency• Demonstrated and in volume over wide power levels
Quality & Reliability	<ul style="list-style-type: none">• JEDEC + AEC-Q101, best-in-class robustness• < 0.2 FIT > 60B hours
Volume Production Capability	<ul style="list-style-type: none">• In-house GaN supply, vertically integrated value chain• Capacity to support higher unit volumes
Comprehensive Product Portfolio	<ul style="list-style-type: none">• Products span low-to-high power, 45W to +10kW• Only company with 900V GaN, 1200V and short circuit in R&D
Ease of Drivability and Design-in	<ul style="list-style-type: none">• Compatibility with standard Silicon packages w/ superior thermal heatsink capability• Growing number of reference designs and IC partners
Patent & IP Coverage	<ul style="list-style-type: none">• Industry's strongest GaN IP position with >1K patents• From material and process to design and application

Myths/Mis-information

Myths Clarified: “IC” or Discrete Integrated or Other – Performance/Ease of Use/Reliability/Cost is what matters

Normally off:
“e-mode/
d-mode”

Fact:

Customer/Application demands Normally off Transistor.

TGAN FETs are Normally Off - just like MOSFETS

TPH GaN FET vs
GaN E-mode/IC
Performance

Fact:

GaN FET solution proven higher performance.

For example, in comparable adapter solutions.
Higher power: TGAN wins (e-mode not there today)

Drivers/
Integration

Fact:

Many modern controllers have drivers integrated (free)

TGAN FETs – Integrated Si

TGAN FETs – No extra driver or interfacing need, and where drivers needed, it is a Silicon-like interface.